ASSOCIATION CONNECT	© Copyright 2005. IPC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater						als and Mf	g Info	rmation		
Supplier Infor	mation						·									
Company name* Company				mpany unique ID U			Unique ID Authority					Response Date*				
onsemi												2025-06-06				
Contact Name			Title - Conta	Title - Contact			Phone - Contact*					Email - Contact*				
Product-Env-Stev	wards	Product Enviro Compliance			N	NA					Product-Env-Stewards@onsemi.com					
Authorized Representative* Tit				Title - Representative			Phone - Representative*				Email - Representative*					
Product-Env-Stev	wards	Product Enviro Compliance			N	NA				Product-Env-Stewards@onsemi.com						
Reques	ster Item Number	Mfr Item	em Number Mfr Item Name				Effective Dat	ve Date Version N		Manufacturing Site		V	Weight* UOM		Unit Type	
		NSPU3051N2T5G Uni-directional DFN			urge Protection Diode	e 0402	2025-06-06 CN1		CN1		0.85			mg	Each	
Ianufacturing	g Proccess Information	on														
Termina	al Plating / Grid Array Material		Terminal Base Alloy J		J-STD-020 MSL Rating		Peak Process Body Temperat		emperatur	ure Max Time at Peak Tem		Temperatu	ature Number of Reflow Cycles		les	
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 1		1		260		С		30 seco		ls 3	3		
Comments																
vel 1 - maximum	n time at peak temperature	during so	ldering is 10-3	30 seconds												
or more informa	ation regarding material co	mposition	please refer to	page 3												·

RoHS Material Composition Declaration			Declaration Type *	Detail	ed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).												
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier has not orditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.												
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted							
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.												
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.05	mg	Supplier	Silicon (Si)	7440-21-3		0.05	mg
Die Attach	0.02	mg	Supplier	Silver (Ag)	7440-22-4		0.015	mg
			Supplier	Epoxy resins	129915-35-1		0.005	mg
Lead Frame	0.41		Supplier	Magnesium (Mg)	7439-95-4		0.0006	mg
			Supplier	Silicon (Si)	7440-21-3		0.0027	mg
			В	Nickel (Ni)	7440-02-0		0.0123	mg
			Supplier	Copper (Cu)	7440-50-8		0.3944	mg
Mold Compound-Black	0.34	mg		Epoxy resin	proprietary data		0.016	mg
			Supplier	Phenol Resin	Proprietary Data		0.016	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0003	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0.3077	mg
Plating	0.02	mg	Supplier	Palladium (Pd)	7440-05-3		0.0015	mg
			В	Nickel (Ni)	7440-02-0		0.0182	mg
			Supplier	Gold (Au)	7440-57-5		0.0003	mg
Wire Bond - Cu	0.01	mg	Supplier	Copper (Cu)	7440-50-8		0.01	mg